

Bill of Materials

TI DESIGNS
PMP7916

Designator	PartNumber	Description
AA1	551XX7850-001 REV B	Printed Circuit Board
C1	GRM2165C2A471JA01D	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805
C2	GRM2165C2A471JA01D	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805
C3	10SVPS330M	CAP, AL, 330uF, 10V, +/-20%, SMD
C4	16SVP180MX	CAP, AL, 180uF, 16V, +/-20%, SMD
C5	16SVP180MX	CAP, AL, 180uF, 16V, +/-20%, SMD
C6	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206
C7	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206
C8	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206
C9	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206
C10	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206
C11	GRM188R71E474KA12D	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603
C12	GRM1885C1H101JA01D	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603
C13	GRM188R71E474KA12D	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603
C14	GRM188R71E105KA12D	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603
C15	GRM188R71E104KA01D	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603
C16	GRM1885C1H101JA01D	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603
C17	GRM188R71E473KA01D	CAP, CERM, 0.047uF, 25V, +/-10%, X7R, 0603
C18	06035A471JAT2A	CAP, CERM, 470pF, 50V, +/-5%, C0G/NP0, 0603
C19	GRM2165C2A471JA01D	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805
C20	C0603C104K5RACTU	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603
C21	GRM2165C2A471JA01D	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805
C22	16SVP180MX	CAP, AL, 180uF, 16V, +/-20%, SMD
C23	16SVP180MX	CAP, AL, 180uF, 16V, +/-20%, SMD
C24	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206

AA1	551XX7850-001 REV B	Printed Circuit Board
C25	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206
C26	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206
C27	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206
C28	C3216X5R1C106M	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206
C29	GRM188R71E474KA12D	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603
C30	GRM1885C1H101JA01D	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603
C31	GRM188R71E474KA12D	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603
C32	GRM188R71E105KA12D	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603
C33	GRM1885C1H101JA01D	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603
C34	GRM188R71C103KA01D	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0603
D1	PMEG6010CEH,115	Diode, Schottky, 60V, 1A, SOD-123F
D3	PMEG6010CEH,115	Diode, Schottky, 60V, 1A, SOD-123F
D4	PMEG6010CEH,115	Diode, Schottky, 60V, 1A, SOD-123F
D5	PMEG6010CEH,115	Diode, Schottky, 60V, 1A, SOD-123F
IN1	5002	Test Point, TH, Miniature, White
J1	575-4	Standard Banana Jack, Uninsulated, 5.5mm
J2	575-4	Standard Banana Jack, Uninsulated, 5.5mm
J3	575-4	Standard Banana Jack, Uninsulated, 5.5mm
J4	575-4	Standard Banana Jack, Uninsulated, 5.5mm
Jx	TSW-102-07-G-S	Header, TH, 100mil, 2x1, Gold plated, 230 mil above insulator
L1	SER2918H-472KL	Inductor, Shielded E Core, Ferrite, 4.7uH, 28A, 0.0026 ohm, SMD
L2	SER2918H-472KL	Inductor, Shielded E Core, Ferrite, 4.7uH, 28A, 0.0026 ohm, SMD
OUT1	5002	Test Point, TH, Miniature, White
Q1	CSD16415Q5	MOSFET N-CH 25V 8SON
Q2	CSD16415Q5	MOSFET N-CH 25V 8SON
Q3	CSD16415Q5	MOSFET N-CH 25V 8SON
Q4	CSD16415Q5	MOSFET N-CH 25V 8SON
Q5	CSD16415Q5	MOSFET N-CH 25V 8SON
Q6	CSD16415Q5	MOSFET N-CH 25V 8SON
Q7	CSD16415Q5	MOSFET N-CH 25V 8SON
Q8	CSD16415Q5	MOSFET N-CH 25V 8SON
Qx	2N7002E-T1-E3	MOSFET, N-CH, 60V, 0.24A, SOT-23
R1	ERJ-12ZYJ7R5U	RESISTOR 7.5 OHM 3/4W 5% 2010

AA1	551XX7850-001 REV B	Printed Circuit Board
R2	ERJ-12ZYJ7R5U	RESISTOR 7.5 OHM 3/4W 5% 2010
R3	ERJ-M1WTF1M5U	RES, 0.0015 ohm, 1%, 1W, 2512
R4	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R5	CRCW0603100RFKEA	RES, 100 ohm, 1%, 0.1W, 0603
R6	CRCW0603100RFKEA	RES, 100 ohm, 1%, 0.1W, 0603
R7	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R8	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R9	CRCW0603158KFKEA	RES, 158k ohm, 1%, 0.1W, 0603
R10	CRCW060349K9FKEA	RES, 49.9k ohm, 1%, 0.1W, 0603
R11	CRCW06033R30JNEA	RES, 3.3 ohm, 5%, 0.1W, 0603
R12	RC0603FR-0715KL	RES, 15.0k ohm, 1%, 0.1W, 0603
R13	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R14	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R15	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R16	CRCW060336K5FKEA	RES, 36.5k ohm, 1%, 0.1W, 0603
R17	CRCW060378K7FKEA	RES, 78.7k ohm, 1%, 0.1W, 0603
R18	CRCW06032K21FKEA	RES, 2.21k ohm, 1%, 0.1W, 0603
R19	ERJ-12ZYJ7R5U	RESISTOR 7.5 OHM 3/4W 5% 2010
R20	CRCW06032K67FKEA	RES, 2.67k ohm, 1%, 0.1W, 0603
R21	CRCW060323K2FKEA	RES, 23.2k ohm, 1%, 0.1W, 0603
R22	CRCW0805604RFKEA	RES, 604 ohm, 1%, 0.125W, 0805
R23	ERJ-12ZYJ7R5U	RESISTOR 7.5 OHM 3/4W 5% 2010
R24	ERJ-M1WTF1M5U	RES, 0.0015 ohm, 1%, 1W, 2512
R25	CRCW0603100RFKEA	RES, 100 ohm, 1%, 0.1W, 0603
R26	CRCW0603100RFKEA	RES, 100 ohm, 1%, 0.1W, 0603
R27	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R28	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R29	CRCW06033R30JNEA	RES, 3.3 ohm, 5%, 0.1W, 0603
R30	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R31	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R32	ERJ-3GEY0R00V	RES, 0 ohm, 5%, 0.1W, 0603
R33	CRCW060336K5FKEA	RES, 36.5k ohm, 1%, 0.1W, 0603
R34	CRCW060378K7FKEA	RES, 78.7k ohm, 1%, 0.1W, 0603

AA1	551XX7850-001 REV B	Printed Circuit Board
Rx	CRCW120610K0FKEA	RES, 10.0k ohm, 1%, 0.25W, 1206
Sync In 1	5002	Test Point, TH, Miniature, White
Sync In 2	5002	Test Point, TH, Miniature, White
TP5	5002	Test Point, TH, Miniature, White
TP6	5002	Test Point, TH, Miniature, White
TPx	5002	Test Point, TH, Miniature, White
U1	LM5122MH	Synchronous Boost Controller
U2	LM5122MH	Synchronous Boost Controller
Vin1	5000	Test Point, TH, Miniature, Red
Vin Gnd1	5001	Test Point, TH, Miniature, Black
Vout1	5000	Test Point, TH, Miniature, Red
Vout Gnd1	5001	Test Point, TH, Miniature, Black

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